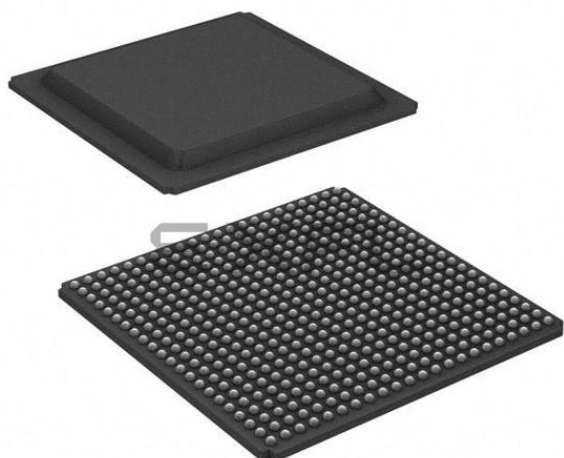




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	5831
Number of Logic Elements/Cells	74637
Total RAM Bits	3170304
Number of I/O	280
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc6slx75-2fg484i

Table 5: Typical Quiescent Supply Current (Cont'd)

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
I _{CCAUXQ}	Quiescent V _{CCAUX} supply current	LX4	2.5	2.5	2.5	2.5	mA
		LX9	2.5	2.5	2.5	2.5	mA
		LX16	3.0	3.0	3.0	3.0	mA
		LX25	4.0	4.0	4.0	4.0	mA
		LX25T	4.0	4.0	4.0	N/A	mA
		LX45	5.0	5.0	5.0	5.0	mA
		LX45T	5.0	5.0	5.0	N/A	mA
		LX75	7.0	7.0	7.0	7.0	mA
		LX75T	7.0	7.0	7.0	N/A	mA
		LX100	9.0	9.0	9.0	9.0	mA
		LX100T	9.0	9.0	9.0	N/A	mA
		LX150	12.0	12.0	12.0	12.0	mA
		LX150T	12.0	12.0	12.0	N/A	mA

Notes:

- Typical values are specified at nominal voltage, 25°C junction temperatures (T_j). Industrial (I) grade devices have the same typical values as commercial (C) grade devices at 25°C, but higher values at 100°C. Use the XPE tool to calculate 100°C values. Nominal V_{CCINT} is 1.20V; use the XPE tool to calculate 1.23V values for the nominal V_{CCINT} of the extended performance range.
- Typical values are for blank configured devices with no output current loads, no active input pull-up resistors, all I/O pins are 3-state and floating.
- If differential signaling is used, more accurate quiescent current estimates can be obtained by using the XPOWER Estimator (XPE) or XPOWER Analyzer (XPA) tools.

Table 6: Power Supply Ramp Time

Symbol	Description	Speed Grade	Ramp Time	Units
V _{CCINTR}	Internal supply voltage ramp time	-3, -3N, -2	0.20 to 50.0	ms
		-1L	0.20 to 40.0	ms
V _{CCO2} ⁽¹⁾	Output drivers bank 2 supply voltage ramp time	All	0.20 to 50.0	ms
V _{CCAUXR}	Auxiliary supply voltage ramp time	All	0.20 to 50.0	ms

Notes:

- The minimum V_{CCO2} for power-on reset and configuration is 1.65V.
- Spartan-6 FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply. Use the XPOWER Estimator (XPE) or XPOWER Analyzer (XPA) tools to estimate current drain on these supplies. Spartan-6 devices do not have a required power-on sequence.

SelectIO™ Interface DC Input and Output Levels

Table 7: Recommended Operating Conditions for User I/Os Using Single-Ended Standards

I/O Standard	V _{CCO} for Drivers ⁽¹⁾			V _{REF} for Inputs		
	V, Min	V, Nom	V, Max	V, Min	V, Nom	V, Max
LVTTTL	3.0	3.3	3.45	V _{REF} is not used for these I/O standards		
LVC MOS33	3.0	3.3	3.45			
LVC MOS25	2.3	2.5	2.7			
LVC MOS18	1.65	1.8	1.95			
LVC MOS18_JEDEC	1.65	1.8	1.95			
LVC MOS15	1.4	1.5	1.6			
LVC MOS15_JEDEC	1.4	1.5	1.6			
LVC MOS12	1.1	1.2	1.3			
LVC MOS12_JEDEC	1.1	1.2	1.3			
PCI33_3 ⁽²⁾	3.0	3.3	3.45			
PCI66_3 ⁽²⁾	3.0	3.3	3.45			
I2C	2.7	3.0	3.45			
SMBUS	2.7	3.0	3.45			
SDIO	3.0	3.3	3.45			
MOBILE_DDR	1.7	1.8	1.9			
HSTL_I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL_II	1.4	1.5	1.6	0.68	0.75	0.9
HSTL_III	1.4	1.5	1.6	–	0.9	–
HSTL_I_18	1.7	1.8	1.9	0.8	0.9	1.1
HSTL_II_18	1.7	1.8	1.9	–	0.9	–
HSTL_III_18	1.7	1.8	1.9	–	1.1	–
SSTL3_I	3.0	3.3	3.45	1.3	1.5	1.7
SSTL3_II	3.0	3.3	3.45	1.3	1.5	1.7
SSTL2_I	2.3	2.5	2.7	1.13	1.25	1.38
SSTL2_II	2.3	2.5	2.7	1.13	1.25	1.38
SSTL18_I	1.7	1.8	1.9	0.833	0.9	0.969
SSTL18_II	1.7	1.8	1.9	0.833	0.9	0.969
SSTL15_II	1.425	1.5	1.575	0.69	0.75	0.81

Notes:

1. V_{CCO} range required when using I/O standard for an output. Also required for MOBILE_DDR, PCI33_3, LVC MOS18_JEDEC, LVC MOS15_JEDEC, and LVC MOS12_JEDEC inputs, and for LVC MOS25 inputs when V_{CCAUX} = 3.3V.
2. For PCI systems, the transmitter and receiver should have common supplies for V_{CCO}.

Table 8: Recommended Operating Conditions for User I/Os Using Differential Signal Standards

I/O Standard	V _{CCO} for Drivers		
	V, Min	V, Nom	V, Max
LVDS_33	3.0	3.3	3.45
LVDS_25	2.25	2.5	2.75
BLVDS_25	2.25	2.5	2.75
MINI_LVDS_33	3.0	3.3	3.45
MINI_LVDS_25	2.25	2.5	2.75
LVPECL_33 ⁽¹⁾	N/A—Inputs Only		
LVPECL_25	N/A—Inputs Only		
RSDS_33	3.0	3.3	3.45
RSDS_25	2.25	2.5	2.75
TMDS_33 ⁽¹⁾	3.14	3.3	3.45
PPDS_33	3.0	3.3	3.45
PPDS_25	2.25	2.5	2.75
DISPLAY_PORT	2.3	2.5	2.7
DIFF_MOBILE_DDR	1.7	1.8	1.9
DIFF_HSTL_I	1.4	1.5	1.6
DIFF_HSTL_II	1.4	1.5	1.6
DIFF_HSTL_III	1.4	1.5	1.6
DIFF_HSTL_I_18	1.7	1.8	1.9
DIFF_HSTL_II_18	1.7	1.8	1.9
DIFF_HSTL_III_18	1.7	1.8	1.9
DIFF_SSTL3_I	3.0	3.3	3.45
DIFF_SSTL3_II	3.0	3.3	3.45
DIFF_SSTL2_I	2.3	2.5	2.7
DIFF_SSTL2_II	2.3	2.5	2.7
DIFF_SSTL18_I	1.7	1.8	1.9
DIFF_SSTL18_II	1.7	1.8	1.9
DIFF_SSTL15_II	1.425	1.5	1.575

Notes:

1. LVPECL_33 and TMDS_33 inputs require V_{CCAUX} = 3.3V nominal.

Table 10: Differential I/O Standard DC Input and Output Levels

I/O Standard	V _{ID}		V _{ICM}		V _{OD}		V _{OCM}		V _{OH}	V _{OL}
	mV, Min	mV, Max	V, Min	V, Max	mV, Min	mV, Max	V, Min	V, Max	V, Min	V, Max
LVDS_33 ⁽²⁾⁽³⁾	100	600	0.3	2.35	247	454	1.125	1.375	–	–
LVDS_25 ⁽²⁾⁽³⁾	100	600	0.3	2.35	247	454	1.125	1.375	–	–
BLVDS_25 ⁽²⁾⁽³⁾	100	–	0.3	2.35	240	460	Typical 50% V _{CCO}		–	–
MINI_LVDS_33	200	600	0.3	1.95	300	600	1.0	1.4	–	–
MINI_LVDS_25	200	600	0.3	1.95	300	600	1.0	1.4	–	–
LVPECL_33 ⁽²⁾⁽³⁾	100	1000	0.3	2.8 ⁽¹⁾	Inputs only					
LVPECL_25 ⁽²⁾⁽³⁾	100	1000	0.3	1.95	Inputs only					
RSDS_33 ⁽²⁾⁽³⁾	100	–	0.3	1.5	100	400	1.0	1.4	–	–
RSDS_25 ⁽²⁾⁽³⁾	100	–	0.3	1.5	100	400	1.0	1.4	–	–
TMDS_33	150	1200	2.7	3.23 ⁽¹⁾	400	800	V _{CCO} – 0.405	V _{CCO} – 0.190	–	–
PPDS_33 ⁽²⁾⁽³⁾	100	400	0.2	2.3	100	400	0.5	1.4	–	–
PPDS_25 ⁽²⁾⁽³⁾	100	400	0.2	2.3	100	400	0.5	1.4	–	–
DISPLAY_PORT	190	1260	0.3	2.35	–	–	Typical 50% V _{CCO}		–	–
DIFF_MOBILE_DDR	100	–	0.78	1.02	–	–	–	–	90% V _{CCO}	10% V _{CCO}
DIFF_HSTL_I	100	–	0.68	0.9	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_HSTL_II	100	–	0.68	0.9	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_HSTL_III	100	–	0.68	0.9	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_HSTL_I_18	100	–	0.8	1.1	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_HSTL_II_18	100	–	0.8	1.1	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_HSTL_III_18	100	–	0.8	1.1	–	–	–	–	V _{CCO} – 0.4	0.4
DIFF_SSTL3_I	100	–	1.0	1.9	–	–	–	–	V _{TT} + 0.6	V _{TT} – 0.6
DIFF_SSTL3_II	100	–	1.0	1.9	–	–	–	–	V _{TT} + 0.8	V _{TT} – 0.8
DIFF_SSTL2_I	100	–	1.0	1.5	–	–	–	–	V _{TT} + 0.61	V _{TT} – 0.61
DIFF_SSTL2_II	100	–	1.0	1.5	–	–	–	–	V _{TT} + 0.81	V _{TT} – 0.81
DIFF_SSTL18_I	100	–	0.7	1.1	–	–	–	–	V _{TT} + 0.47	V _{TT} – 0.47
DIFF_SSTL18_II	100	–	0.7	1.1	–	–	–	–	V _{TT} + 0.6	V _{TT} – 0.6
DIFF_SSTL15_II	100	–	0.55	0.95	–	–	–	–	V _{TT} + 0.4	V _{TT} – 0.4

Notes:

1. LVPECL_33 and TMDS_33 maximum V_{ICM} is the lower of V (maximum) or V_{CCAUX} – (V_{ID}/2)
2. When V_{CCAUX} = 3.3V, the DCD can be higher than 5% for V_{ICM} < 0.7V when using these I/O standards: LVDS_25, LVDS_33, BLVDS_25, LVPECL_25, LVPECL_33, RSDS_25, RSDS_33, PPDS_25, and PPDS_33.
3. The -1L devices require V_{CCAUX} = 2.5V when using the LVDS_25, LVDS_33, BLVDS_25, LVPECL_25, RSDS_25, RSDS_33, PPDS_25, and PPDS_33 I/O standards on inputs. LVPECL_33 is not supported in the -1L devices.

Table 21: GTP Transceiver User Clock Switching Characteristics⁽¹⁾

Symbol	Description	Conditions	Speed Grade				Units
			-3	-3N	-2	-1L	
F _{TXOUT}	TXOUTCLK maximum frequency		320	320	270	N/A	MHz
F _{RXREC}	RXRECCLK maximum frequency		320	320	270	N/A	MHz
T _{RX}	RXUSRCLK maximum frequency		320	320	270	N/A	MHz
T _{RX2}	RXUSRCLK2 maximum frequency	1 byte interface	156.25	156.25	125	N/A	MHz
		2 byte interface	160	160	125	N/A	MHz
		4 byte interface	80	80	67.5	N/A	MHz
T _{TX}	TXUSRCLK maximum frequency		320	320	270	N/A	MHz
T _{TX2}	TXUSRCLK2 maximum frequency	1 byte interface	156.25	156.25	125	N/A	MHz
		2 byte interface	160	160	125	N/A	MHz
		4 byte interface	80	80	67.5	N/A	MHz

Notes:

1. Clocking must be implemented as described in [UG386: Spartan-6 FPGA GTP Transceivers User Guide](#).

Table 22: GTP Transceiver Transmitter Switching Characteristics

Symbol	Description	Condition	Min	Typ	Max	Units
T _{RTX}	TX Rise time	20%–80%	–	140	–	ps
T _{FTX}	TX Fall time	80%–20%	–	120	–	ps
T _{LLSKEW}	TX lane-to-lane skew ⁽¹⁾		–	–	400	ps
V _{TXOOBVDPP}	Electrical idle amplitude		–	–	20	mV
T _{TXOOBTRANSITION}	Electrical idle transition time		–	–	50	ns
T _{J3.125}	Total Jitter ⁽²⁾	3.125 Gb/s	–	–	0.35	UI
D _{J3.125}	Deterministic Jitter ⁽²⁾		–	–	0.15	UI
T _{J2.5}	Total Jitter ⁽²⁾	2.5 Gb/s	–	–	0.33	UI
D _{J2.5}	Deterministic Jitter ⁽²⁾		–	–	0.15	UI
T _{J1.62}	Total Jitter ⁽²⁾	1.62 Gb/s	–	–	0.20	UI
D _{J1.62}	Deterministic Jitter ⁽²⁾		–	–	0.10	UI
T _{J1.25}	Total Jitter ⁽²⁾	1.25 Gb/s	–	–	0.20	UI
D _{J1.25}	Deterministic Jitter ⁽²⁾		–	–	0.10	UI
T _{J614}	Total Jitter ⁽²⁾	614 Mb/s	–	–	0.10	UI
D _{J614}	Deterministic Jitter ⁽²⁾		–	–	0.05	UI

Notes:

1. Using same REFCLK input with TXENPMAPHASEALIGN enabled for up to four consecutive GTP transceiver sites.
2. Using PLL_DIVSEL_FB = 2, INTDATAWIDTH = 1. These values are NOT intended for protocol specific compliance determinations.

Performance Characteristics

This section provides the performance characteristics of some common functions and designs implemented in Spartan-6 devices. The numbers reported here are worst-case values; they have all been fully characterized. These values are subject to the same guidelines as the [Switching Characteristics, page 19](#).

Table 25: Interface Performances

Description	I/O Resource	Clock Buffer	Data Width	Speed Grade				Units
				-3	-3N	-2	-1L	
Networking Applications ⁽¹⁾								
SDR LVDS transmitter or receiver	IOB SDR register	BUFG	–	400	400	375	250	Mb/s
DDR LVDS transmitter or receiver	ODDR2/IDDR2 register	2 BUFPGs	–	800	800	750	500	Mb/s
SDR LVDS transmitter	OSERDES2	BUFPLL	2	500	500	500	250	Mb/s
			3	750	750	750	375	Mb/s
			4-8	1080	1050	950	500	Mb/s
DDR LVDS transmitter	OSERDES2	2 BUFIO2s	2	500	500	500	250	Mb/s
			3	750	750	750	375	Mb/s
			4-8	1080	1050	950	500	Mb/s
SDR LVDS receiver	ISERDES2 in RETIMED mode	BUFPLL	2	500	500	500	—	Mb/s
			3	750	750	750	—	Mb/s
			4-8	1080	1050	950	—	Mb/s
DDR LVDS receiver	ISERDES2 in RETIMED mode	2 BUFIO2s	2	500	500	500	—	Mb/s
			3	750	750	750	—	Mb/s
			4-8	1080	1050	950	—	Mb/s
Memory Interfaces (Implemented using the Spartan-6 FPGA Memory Controller Block) ⁽²⁾								
Standard Performance (Standard V _{CCINT})								
DDR				400	Note 4	400	350	Mb/s
DDR2				667	Note 4	625	400	Mb/s
DDR3				800	Note 4	667	—	Mb/s
LPDDR (Mobile_DDR)				400	Note 4	400	350	Mb/s
Extended Performance (Requires Extended Performance V _{CCINT}) ⁽³⁾								
DDR2				800	Note 4	667	—	Mb/s

Notes:

1. Refer to [XAPP1064](#), *Source-Synchronous Serialization and Deserialization (up to 1050 Mb/s)* and [UG381](#), *Spartan-6 FPGA SelectIO Resources User Guide*.
2. Refer to [UG388](#), *Spartan-6 FPGA Memory Controller User Guide*.
3. Extended Memory Controller block performance for DDR2 can be achieved using the extended performance V_{CCINT} range from [Table 2](#).
4. The LX4 device, all devices in the TQG144 and CPG196 packages, and the -3N speed grade do not support a Memory Controller Block.

Production Silicon and ISE Software Status

In some cases, a particular family member (and speed grade) is released to production before a speed specification is released with the correct label (Advance, Preliminary, Production). Any labeling discrepancies are corrected in subsequent speed specification releases. [Table 27](#) lists the production released Spartan-6 family member, speed grade, and the minimum corresponding supported speed specification version and ISE® software revisions. The ISE software and speed specifications listed are the minimum releases required for production. All subsequent releases of software and speed specifications are valid.

Table 27: Spartan-6 Device Production Software and Speed Specification Release⁽¹⁾

Device	Speed Grade Designations ⁽²⁾			
	-3 ⁽³⁾	-3N	-2 ⁽⁴⁾	-1L
XC6SLX4	ISE 12.4 v1.15	N/A	ISE 12.3 v1.12 ⁽⁵⁾	ISE 13.2 v1.07
XC6SLX9	ISE 12.4 v1.15	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.3 v1.12 ⁽⁵⁾	ISE 13.2 v1.07
XC6SLX16	ISE 12.1 v1.08	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 11.5 v1.06	ISE 13.2 v1.07
XC6SLX25	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.2 v1.07
XC6SLX25T	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	N/A
XC6SLX45	ISE 12.1 v1.08	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 11.5 v1.07	ISE 13.1 v1.06
XC6SLX45T	ISE 12.1 v1.08	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.1 v1.08	N/A
XC6SLX75	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.2 v1.07
XC6SLX75T	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	N/A
XC6SLX100	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 v1.06
XC6SLX100T	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	N/A
XC6SLX150	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 v1.06
XC6SLX150T	ISE 12.2 v1.11 ⁽⁶⁾	ISE 13.1 Update v1.18 ⁽⁷⁾	ISE 12.2 v1.11 ⁽⁶⁾	N/A
XA6SLX4	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX9	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX16	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX25	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX25T	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX45	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX45T	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX75	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX75T	ISE 13.2 v1.19	N/A	ISE 13.2 v1.19	N/A
XA6SLX100	N/A	N/A	ISE 13.3 v1.20	N/A

Table 28: IOB Switching Characteristics for the Commercial (XC) Spartan-6 Devices (Cont'd)

I/O Standard	T _{IOPI}				T _{IOOP}				T _{IOTP}				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-3N	-2	-1L ⁽¹⁾	-3	-3N	-2	-1L ⁽¹⁾	-3	-3N	-2	-1L ⁽¹⁾	
LVTTL, QUIETIO, 2 mA	1.35	1.47	1.60	1.82	5.39	5.53	5.73	6.37	5.39	5.53	5.73	6.37	ns
LVTTL, QUIETIO, 4 mA	1.35	1.47	1.60	1.82	4.29	4.43	4.63	5.22	4.29	4.43	4.63	5.22	ns
LVTTL, QUIETIO, 6 mA	1.35	1.47	1.60	1.82	3.75	3.89	4.09	4.69	3.75	3.89	4.09	4.69	ns
LVTTL, QUIETIO, 8 mA	1.35	1.47	1.60	1.82	3.23	3.37	3.57	4.20	3.23	3.37	3.57	4.20	ns
LVTTL, QUIETIO, 12 mA	1.35	1.47	1.60	1.82	3.28	3.42	3.62	4.22	3.28	3.42	3.62	4.22	ns
LVTTL, QUIETIO, 16 mA	1.35	1.47	1.60	1.82	2.94	3.08	3.28	3.92	2.94	3.08	3.28	3.92	ns
LVTTL, QUIETIO, 24 mA	1.35	1.47	1.60	1.82	2.69	2.83	3.03	3.67	2.69	2.83	3.03	3.67	ns
LVTTL, Slow, 2 mA	1.35	1.47	1.60	1.82	4.36	4.50	4.70	5.30	4.36	4.50	4.70	5.30	ns
LVTTL, Slow, 4 mA	1.35	1.47	1.60	1.82	3.17	3.31	3.51	4.16	3.17	3.31	3.51	4.16	ns
LVTTL, Slow, 6 mA	1.35	1.47	1.60	1.82	2.76	2.90	3.10	3.75	2.76	2.90	3.10	3.75	ns
LVTTL, Slow, 8 mA	1.35	1.47	1.60	1.82	2.59	2.73	2.93	3.55	2.59	2.73	2.93	3.55	ns
LVTTL, Slow, 12 mA	1.35	1.47	1.60	1.82	2.58	2.72	2.92	3.54	2.58	2.72	2.92	3.54	ns
LVTTL, Slow, 16 mA	1.35	1.47	1.60	1.82	2.39	2.53	2.73	3.40	2.39	2.53	2.73	3.40	ns
LVTTL, Slow, 24 mA	1.35	1.47	1.60	1.82	2.28	2.42	2.62	3.24	2.28	2.42	2.62	3.24	ns
LVTTL, Fast, 2 mA	1.35	1.47	1.60	1.82	3.78	3.92	4.12	4.74	3.78	3.92	4.12	4.74	ns
LVTTL, Fast, 4 mA	1.35	1.47	1.60	1.82	2.49	2.63	2.83	3.45	2.49	2.63	2.83	3.45	ns
LVTTL, Fast, 6 mA	1.35	1.47	1.60	1.82	2.44	2.58	2.78	3.40	2.44	2.58	2.78	3.40	ns
LVTTL, Fast, 8 mA	1.35	1.47	1.60	1.82	2.32	2.46	2.66	3.28	2.32	2.46	2.66	3.28	ns
LVTTL, Fast, 12 mA	1.35	1.47	1.60	1.82	1.83	1.97	2.17	2.79	1.83	1.97	2.17	2.79	ns
LVTTL, Fast, 16 mA	1.35	1.47	1.60	1.82	1.83	1.97	2.17	2.79	1.83	1.97	2.17	2.79	ns
LVTTL, Fast, 24 mA	1.35	1.47	1.60	1.82	1.83	1.97	2.17	2.79	1.83	1.97	2.17	2.79	ns
LVC MOS33, QUIETIO, 2 mA	1.34	1.46	1.59	1.82	5.40	5.54	5.74	6.37	5.40	5.54	5.74	6.37	ns
LVC MOS33, QUIETIO, 4 mA	1.34	1.46	1.59	1.82	4.03	4.17	4.37	5.01	4.03	4.17	4.37	5.01	ns
LVC MOS33, QUIETIO, 6 mA	1.34	1.46	1.59	1.82	3.51	3.65	3.85	4.47	3.51	3.65	3.85	4.47	ns
LVC MOS33, QUIETIO, 8 mA	1.34	1.46	1.59	1.82	3.37	3.51	3.71	4.33	3.37	3.51	3.71	4.33	ns
LVC MOS33, QUIETIO, 12 mA	1.34	1.46	1.59	1.82	2.94	3.08	3.28	3.93	2.94	3.08	3.28	3.93	ns
LVC MOS33, QUIETIO, 16 mA	1.34	1.46	1.59	1.82	2.77	2.91	3.11	3.78	2.77	2.91	3.11	3.78	ns
LVC MOS33, QUIETIO, 24 mA	1.34	1.46	1.59	1.82	2.59	2.73	2.93	3.58	2.59	2.73	2.93	3.58	ns
LVC MOS33, Slow, 2 mA	1.34	1.46	1.59	1.82	4.37	4.51	4.71	5.28	4.37	4.51	4.71	5.28	ns
LVC MOS33, Slow, 4 mA	1.34	1.46	1.59	1.82	2.98	3.12	3.32	3.94	2.98	3.12	3.32	3.94	ns
LVC MOS33, Slow, 6 mA	1.34	1.46	1.59	1.82	2.58	2.72	2.92	3.61	2.58	2.72	2.92	3.61	ns
LVC MOS33, Slow, 8 mA	1.34	1.46	1.59	1.82	2.65	2.79	2.99	3.61	2.65	2.79	2.99	3.61	ns
LVC MOS33, Slow, 12 mA	1.34	1.46	1.59	1.82	2.39	2.53	2.73	3.31	2.39	2.53	2.73	3.31	ns
LVC MOS33, Slow, 16 mA	1.34	1.46	1.59	1.82	2.31	2.45	2.65	3.27	2.31	2.45	2.65	3.27	ns
LVC MOS33, Slow, 24 mA	1.34	1.46	1.59	1.82	2.28	2.42	2.62	3.24	2.28	2.42	2.62	3.24	ns
LVC MOS33, Fast, 2 mA	1.34	1.46	1.59	1.82	3.76	3.90	4.10	4.70	3.76	3.90	4.10	4.70	ns
LVC MOS33, Fast, 4 mA	1.34	1.46	1.59	1.82	2.48	2.62	2.82	3.44	2.48	2.62	2.82	3.44	ns
LVC MOS33, Fast, 6 mA	1.34	1.46	1.59	1.82	2.32	2.46	2.66	3.28	2.32	2.46	2.66	3.28	ns

Table 29: IOB Switching Characteristics for the Automotive XA Spartan-6 and the Spartan-6Q Devices⁽¹⁾ (Cont'd)

I/O Standard	T _{IOPI}		T _{IOOP}		T _{IOTP}		Units
	Speed Grade		Speed Grade		Speed Grade		
	-3	-2	-3	-2	-3	-2	
LVC MOS15, QUIETIO, 2 mA	1.05	1.23	5.63	5.83	5.63	5.83	ns
LVC MOS15, QUIETIO, 4 mA	1.05	1.23	4.75	4.95	4.75	4.95	ns
LVC MOS15, QUIETIO, 6 mA	1.05	1.23	4.21	4.41	4.21	4.41	ns
LVC MOS15, QUIETIO, 8 mA	1.05	1.23	4.05	4.25	4.05	4.25	ns
LVC MOS15, QUIETIO, 12 mA	1.05	1.23	3.74	3.94	3.74	3.94	ns
LVC MOS15, QUIETIO, 16 mA	1.05	1.23	3.52	3.72	3.52	3.72	ns
LVC MOS15, Slow, 2 mA	1.05	1.23	4.32	4.52	4.32	4.52	ns
LVC MOS15, Slow, 4 mA	1.05	1.23	3.58	3.78	3.58	3.78	ns
LVC MOS15, Slow, 6 mA	1.05	1.23	2.45	2.65	2.45	2.65	ns
LVC MOS15, Slow, 8 mA	1.05	1.23	2.46	2.66	2.46	2.66	ns
LVC MOS15, Slow, 12 mA	1.05	1.23	2.17	2.37	2.17	2.37	ns
LVC MOS15, Slow, 16 mA	1.05	1.23	2.15	2.35	2.15	2.35	ns
LVC MOS15, Fast, 2 mA	1.05	1.23	3.43	3.63	3.43	3.63	ns
LVC MOS15, Fast, 4 mA	1.05	1.23	2.42	2.62	2.42	2.62	ns
LVC MOS15, Fast, 6 mA	1.05	1.23	1.92	2.12	1.92	2.12	ns
LVC MOS15, Fast, 8 mA	1.05	1.23	1.87	2.07	1.87	2.07	ns
LVC MOS15, Fast, 12 mA	1.05	1.23	1.87	2.07	1.87	2.07	ns
LVC MOS15, Fast, 16 mA	1.05	1.23	1.87	2.07	1.87	2.07	ns
LVC MOS15_JEDEC, QUIETIO, 2 mA	1.10	1.28	5.64	5.84	5.64	5.84	ns
LVC MOS15_JEDEC, QUIETIO, 4 mA	1.10	1.28	4.75	4.95	4.75	4.95	ns
LVC MOS15_JEDEC, QUIETIO, 6 mA	1.10	1.28	4.21	4.41	4.21	4.41	ns
LVC MOS15_JEDEC, QUIETIO, 8 mA	1.10	1.28	4.06	4.26	4.06	4.26	ns
LVC MOS15_JEDEC, QUIETIO, 12 mA	1.10	1.28	3.75	3.95	3.75	3.95	ns
LVC MOS15_JEDEC, QUIETIO, 16 mA	1.10	1.28	3.53	3.73	3.53	3.73	ns
LVC MOS15_JEDEC, Slow, 2 mA	1.10	1.28	4.32	4.52	4.32	4.52	ns
LVC MOS15_JEDEC, Slow, 4 mA	1.10	1.28	3.56	3.76	3.56	3.76	ns
LVC MOS15_JEDEC, Slow, 6 mA	1.10	1.28	2.44	2.64	2.44	2.64	ns
LVC MOS15_JEDEC, Slow, 8 mA	1.10	1.28	2.47	2.67	2.47	2.67	ns
LVC MOS15_JEDEC, Slow, 12 mA	1.10	1.28	2.15	2.35	2.15	2.35	ns
LVC MOS15_JEDEC, Slow, 16 mA	1.10	1.28	2.15	2.35	2.15	2.35	ns
LVC MOS15_JEDEC, Fast, 2 mA	1.10	1.28	3.43	3.63	3.43	3.63	ns
LVC MOS15_JEDEC, Fast, 4 mA	1.10	1.28	2.42	2.62	2.42	2.62	ns
LVC MOS15_JEDEC, Fast, 6 mA	1.10	1.28	1.92	2.12	1.92	2.12	ns
LVC MOS15_JEDEC, Fast, 8 mA	1.10	1.28	1.87	2.07	1.87	2.07	ns
LVC MOS15_JEDEC, Fast, 12 mA	1.10	1.28	1.87	2.07	1.87	2.07	ns
LVC MOS15_JEDEC, Fast, 16 mA	1.10	1.28	1.87	2.07	1.87	2.07	ns
LVC MOS12, QUIETIO, 2 mA	0.98	1.16	6.54	6.74	6.54	6.74	ns
LVC MOS12, QUIETIO, 4 mA	0.98	1.16	5.12	5.32	5.12	5.32	ns

I/O Standard Measurement Methodology

Input Delay Measurements

Table 31 shows the test setup parameters used for measuring input delay.

Table 31: Input Delay Measurement Methodology

Description	I/O Standard Attribute	$V_L^{(1)}$	$V_H^{(1)}$	$V_{MEAS}^{(3)(4)}$	$V_{REF}^{(2)(4)}$
LVTTTL (Low-Voltage Transistor-Transistor Logic)	LVTTTL	0	3.0	1.4	—
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	0	3.3	1.65	—
LVC MOS, 2.5V	LVC MOS25	0	2.5	1.25	—
LVC MOS, 1.8V	LVC MOS18	0	1.8	0.9	—
LVC MOS, 1.5V	LVC MOS15	0	1.5	0.75	—
LVC MOS, 1.2V	LVC MOS12	0	1.2	0.6	—
PCI (Peripheral Component Interface), 33 MHz and 66 MHz, 3.3V	PCI33_3, PCI66_3	Per PCI Specification			—
HSTL (High-Speed Transceiver Logic), Class I & II	HSTL_I, HSTL_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL, Class III	HSTL_III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class I & II, 1.8V	HSTL_I_18, HSTL_II_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class III 1.8V	HSTL_III_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	1.1
SSTL (Stub Terminated Transceiver Logic), Class I & II, 3.3V	SSTL3_I, SSTL3_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.5
SSTL, Class I & II, 2.5V	SSTL2_I, SSTL2_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
SSTL, Class I & II, 1.8V	SSTL18_I, SSTL18_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
SSTL, Class II, 1.5V	SSTL15_II	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.75
LVDS (Low-Voltage Differential Signaling), 2.5V & 3.3V	LVDS_25, LVDS_33	$1.25 - 0.125$	$1.25 + 0.125$	0 ⁽⁵⁾	—
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V & 3.3V	LVPECL_25, LVPECL_33	$1.2 - 0.3$	$1.2 + 0.3$	0 ⁽⁵⁾	—
BLVDS (Bus LVDS), 2.5V	BLVDS_25	$1.3 - 0.125$	$1.3 + 0.125$	0 ⁽⁵⁾	—
Mini-LVDS, 2.5V & 3.3V	MINI_LVDS_25, MINI_LVDS_33	$1.2 - 0.125$	$1.2 + 0.125$	0 ⁽⁵⁾	—
RS DS (Reduced Swing Differential Signaling), 2.5V & 3.3V	RS DS_25, RS DS_33	$1.2 - 0.1$	$1.2 + 0.1$	0 ⁽⁵⁾	—
TMDS (Transition Minimized Differential Signaling), 3.3V	TMDS_33	$3.0 - 0.1$	$3.0 + 0.1$	0 ⁽⁵⁾	—
PPDS (Point-to-Point Differential Signaling), 2.5V & 3.3V	PPDS_25, PPDS_33	$1.25 - 0.1$	$1.25 + 0.1$	0 ⁽⁵⁾	—

Notes:

1. Input waveform switches between V_L and V_H .
2. Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst case of these measurements. V_{REF} values listed are typical.
3. Input voltage level from which measurement starts.
4. This is an input voltage reference that bears no relation to the V_{REF} / V_{MEAS} parameters found in IBIS models and/or noted in Figure 4.
5. The value given is the differential input voltage.

Table 32: Output Delay Measurement Methodology (Cont'd)

Description	I/O Standard Attribute	R_{REF} (Ω)	$C_{REF}^{(1)}$ (pF)	V_{MEAS} (V)	V_{REF} (V)
SSTL, Class II, 2.5V	SSTL2_II	25	0	V_{REF}	1.25
SSTL, Class II, 1.5V	SSTL15_II	25	0	V_{REF}	0.75
LVDS (Low-Voltage Differential Signaling), 2.5V & 3.3V	LVDS_25, LVDS_33	100	0	0 ⁽³⁾	—
BLVDS (Bus LVDS), 2.5V	BLVDS_25	Note 4	0	0 ⁽³⁾	—
Mini-LVDS, 2.5V & 3.3V	MINI_LVDS_25, MINI_LVDS_33	100	0	0 ⁽³⁾	—
RSDS (Reduced Swing Differential Signaling), 2.5V & 3.3V	RSDS_25, RSDS_33	100	0	0 ⁽³⁾	—
TMDS (Transition Minimized Differential Signaling), 3.3V	TMDS_33	Note 5	0	0 ⁽³⁾	—
PPDS (Point-to-Point Differential Signaling, 2.5V & 3.3V	PPDS_25, PPDS_33	100	0	0 ⁽³⁾	—

Notes:

1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. Per PCI specifications.
3. The value given is the differential output voltage.
4. See the *BLVDS Output Termination* section in [UG381](#), *Spartan-6 FPGA SelectIO Resources User Guide*.
5. See the *TMDS_33 Termination* section in [UG381](#), *Spartan-6 FPGA SelectIO Resources User Guide*.

Simultaneously Switching Outputs

Due to package electrical parasitics, a given package supports a limited number of simultaneous switching outputs (SSOs) when using fast, high-drive outputs. [Table 33](#) and [Table 34](#) provide guidelines for the recommended maximum allowable number of SSOs. These guidelines describe the maximum number of user I/O pins of an output signal standard that should simultaneously switch in the same direction, while maintaining a safe level of switching noise for that particular signal standard. Meeting these guidelines for the stated test conditions ensures that the FPGA operates free from the adverse effects of GND and power bounce.

For each device/package combination, [Table 33](#) provides the number of equivalent V_{CCO} /GND pairs per bank. For each output signal standard and drive strength, [Table 34](#) recommends the maximum number of SSOs, switching in the same direction, allowed per V_{CCO} /GND pair within an I/O bank. The guidelines are categorized by package style, slew rate, and output drive current. The number of SSOs are also specified by I/O bank. Multiply the appropriate numbers from each table to calculate the maximum number of SSOs allowed within an I/O bank. The guidelines assume that all pins within a bank use the same I/O standard. Exceeding these SSO guidelines can result in increased power or GND bounce, degraded signal integrity, or increased system jitter. For a given I/O standard, if the SSO limit per pair in [Table 34](#) is greater than the maximum I/O per pair in [Table 33](#), then there is no SSO limit for the exclusive use of that I/O standard.

The recommended maximum SSO values assume that the FPGA is soldered on a printed circuit board and that the board uses sound design practices. Due to the additional inductance introduced by the socket, the SSO values do not apply for FPGAs mounted in sockets. The SSO values assume that the V_{CCAUX} is powered at 3.3V. Setting V_{CCAUX} to 2.5V provides better SSO characteristics. For more detail, see [UG381](#): *Spartan-6 FPGA SelectIO Resources User Guide*.

Table 34: SSO Limit per V_{CCO}/GND Pair

V_{CCO}	I/O Standard	Drive	Slew	SSO Limit per V_{CCO}/GND Pair			
				All TQG144, CPG196, CSG225, FT(G)256, and LX devices in CSG324		All CS(G)484, FG(G)484, FG(G)676, FG(G)900, and LXT devices in CSG324	
				Bank 0/2	Bank 1/3	Bank 0/2	Bank 1/3/4/5
1.2V	LVCMOS12, LVCMOS12_JEDEC	2	Fast	30 ⁽¹⁾	35	30	35
			Slow	51	55	51	52
			QuietIO	71	58	71	70
		4	Fast	17	17	17	19
			Slow	23	25	23	22
			QuietIO	35	32	35	32
		6	Fast	13	15	13	14
			Slow	19	20	19	17
			QuietIO	26	24	26	24
		8	Fast	N/A	12	N/A	12
			Slow	N/A	15	N/A	13
			QuietIO	N/A	20	N/A	19
		12	Fast	N/A	5	N/A	4
			Slow	N/A	8	N/A	5
			QuietIO	N/A	11	N/A	10

Table 34: SSO Limit per V_{CCO}/GND Pair (Cont'd)

V_{CCO}	I/O Standard	Drive	Slew	SSO Limit per V_{CCO}/GND Pair			
				All TQG144, CPG196, CSG225, FT(G)256, and LX devices in CSG324		All CS(G)484, FG(G)484, FG(G)676, FG(G)900, and LXT devices in CSG324	
				Bank 0/2	Bank 1/3	Bank 0/2	Bank 1/3/4/5
Various	LVDS_33			16	N/A	16	N/A
	LVDS_25			20	N/A	20	N/A
	BLVDS_25			20	48	20	20
	MINI_LVDS_33			13	N/A	13	N/A
	MINI_LVDS_25			18	N/A	18	N/A
	RSDS_33			12	N/A	12	N/A
	RSDS_25			15	N/A	15	N/A
	TMDS_33			83	N/A	83	N/A
	PPDS_33			12	N/A	12	N/A
	PPDS_25			16	N/A	16	N/A
	DISPLAY_PORT			42	40	42	30
	I2C			47	55	47	42
	SMBUS			44	52	44	40

Notes:

- SSO limits greater than the number of I/O per V_{CCO}/GND pair (Table 33) indicate No Limit for the given I/O standard. They are provided in this table to calculate limits when using multiple I/O standards in a bank.
- Not available (N/A) indicates that the I/O standard is not available in the given bank.
- When used with the MCB, these signals are exempt from SSO analysis due to the known activity of the MCB switching patterns. SSO performance is validated for all MCB instances. MCB outputs can, in some cases, exceed the SSO limits.

Input/Output Logic Switching Characteristics

Table 35: ILOGIC2 Switching Characteristics

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
Setup/Hold						
T _{ICE0CK} /T _{ICKCE0}	CE0 pin Setup/Hold with respect to CLK	0.56/ −0.30	0.56/ −0.25	0.79/ −0.22	1.21/ −0.52	ns
T _{ISRCK} /T _{ICKSR}	SR pin Setup/Hold with respect to CLK	0.74/ −0.23	0.74/ −0.22	0.98/ −0.20	1.31/ −0.45	ns
T _{IDOCK} /T _{IOCKD}	D pin Setup/Hold with respect to CLK without Delay	1.19/ −0.83	1.36/ −0.83	1.73/ −0.83	2.18/ −1.77	ns
T _{IDOCKD} /T _{IOCKDD}	DDLY pin Setup/Hold with respect to CLK (using IODELAY2)	0.31/ 0.00	0.47/ 0.00	0.54/ 0.00	0.63/ −0.39	ns
Combinatorial						
T _{IDI}	D pin to O pin propagation delay, no Delay	0.95	1.28	1.53	2.25	ns
T _{IDID}	DDLY pin to O pin propagation delay (using IODELAY2)	0.23	0.39	0.44	0.74	ns
Sequential Delays						
T _{IDLO}	D pin to Q pin using flip-flop as a latch without Delay	1.56	1.86	2.39	3.49	ns
T _{IDLOD}	DDLY pin to Q1 pin using flip-flop as a latch (using IODELAY2)	0.68	0.97	1.20	1.94	ns
T _{ICKQ}	CLK to Q outputs for XC devices	1.03	1.24	1.43	2.11	ns
	CLK to Q outputs for XA and XQ devices	1.38	N/A	1.78	2.11	ns
T _{RQ_ILOGIC2}	SR pin to Q outputs	1.81	1.81	2.50	3.05	ns

Table 36: OLOGIC2 Switching Characteristics

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
Setup/Hold						
T _{ODCK} /T _{OCKD}	D1/D2 pins Setup/Hold with respect to CLK	0.81/ −0.05	0.86/ −0.05	1.18/ 0.00	1.73/ −0.27	ns
T _{OOCECK} /T _{OCKOCE}	OCE pin Setup/Hold with respect to CLK	0.75/ −0.10	0.75/ −0.10	1.01/ −0.05	1.66/ −0.23	ns
T _{OSRCK} /T _{OCKSR}	SR pin Setup/Hold with respect to CLK	0.70/ −0.28	0.79/ −0.28	1.03/ −0.23	1.39/ −0.47	ns
T _{OTCK} /T _{OCKT}	T1/T2 pins Setup/Hold with respect to CLK	0.24/ −0.08	0.56/ −0.06	0.83/ −0.01	0.99/ −0.19	ns
T _{OTCECK} /T _{OCKTCE}	TCE pin Setup/Hold with respect to CLK	0.58/ −0.06	0.72/ −0.06	1.18/ −0.01	1.51/ −0.13	ns
Sequential Delays						
T _{OCKQ}	CLK to OQ/TQ out for XC devices	0.48	0.51	0.74	0.74	ns
	CLK to OQ/TQ out for XA and XQ devices	0.85	N/A	1.16	0.74	ns
T _{RQ_OLOGIC2}	SR pin to OQ/TQ out	1.81	1.81	2.50	3.05	ns

CLB Switching Characteristics (SLICEM Only)

Table 40: CLB Switching Characteristics (SLICEM Only)

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
Combinatorial Delays						
T _{ILO}	An – Dn LUT inputs to A to D outputs	0.21	0.26	0.26	0.46	ns, Max
	An – Dn LUT inputs through F7AMUX/F7BMUX to AMUX/CMUX output	0.37	0.43	0.43	0.77	ns, Max
T _{OPAB}	An – Dn LUT inputs through F7AMUX or F7BMUX and F8MUX to BMUX output	0.37	0.46	0.46	0.84	ns, Max
T _{ITO}	An – Dn LUT inputs through latch to AQ – DQ outputs	0.82	0.95	0.95	1.64	ns, Max
T _{TITO_LOGIC}	An – Dn LUT inputs to AQ – DQ outputs (latch as logic)	0.82	0.95	0.95	1.64	ns, Max
T _{OPCYA}	An LUT inputs to COUT output	0.38	0.48	0.48	0.69	ns, Max
T _{OPCYB}	Bn LUT inputs to COUT output	0.38	0.49	0.49	0.71	ns, Max
T _{OPCYC}	Cn LUT inputs to COUT output	0.28	0.33	0.33	0.55	ns, Max
T _{OPCYD}	Dn LUT inputs to COUT output	0.28	0.35	0.35	0.52	ns, Max
T _{AXCY}	AX input to COUT output	0.21	0.26	0.26	0.36	ns, Max
T _{BXCy}	BX input to COUT output	0.13	0.16	0.16	0.18	ns, Max
T _{CXCy}	CX input to COUT output	0.10	0.12	0.12	0.09	ns, Max
T _{DXCy}	DX input to COUT output	0.09	0.11	0.11	0.09	ns, Max
T _{BYP}	CIN input to COUT output	0.08	0.10	0.10	0.06	ns, Max
T _{CINA}	CIN input to AMUX output	0.21	0.22	0.22	0.47	ns, Max
T _{CINB}	CIN input to BMUX output	0.30	0.31	0.31	0.57	ns, Max
T _{CINC}	CIN input to CMUX output	0.29	0.31	0.31	0.58	ns, Max
T _{CIND}	CIN input to DMUX output	0.31	0.32	0.32	0.68	ns, Max
Sequential Delays						
T _{CKO}	Clock to AQ – DQ outputs	0.45	0.53	0.53	0.74	ns, Max
Setup and Hold Times of CLB Flip-Flops Before/After Clock CLK						
T _{DICK} /T _{CKDI}	AX – DX input to CLK on A – D flip-flops	0.42/ 0.28	0.47/ 0.39	0.47/ 0.39	0.90/ 0.56	ns, Min
T _{CECK} /T _{CKCE}	CE input to CLK on A – D flip-flops	0.31/ –0.07	0.37/ –0.07	0.37/ –0.07	0.59/ –0.27	ns, Min
T _{SRCK} /T _{CKSR}	SR input to CLK on A – D flip-flops for XC devices	0.41/ 0.02	0.42/ 0.02	0.42/ 0.02	0.68/ –0.29	ns, Min
	SR input to CLK on A – D flip-flops for XA and XQ devices	0.41/ 0.02	N/A	0.44/ 0.02	0.68/ –0.29	ns, Min
T _{CINCK} /T _{CKCIN}	CIN input to CLK on A – D flip-flops	0.31/ –0.17	0.31/ –0.13	0.31/ –0.13	0.81/ –0.42	ns, Min
Set/Reset						
T _{RPW}	SR input minimum pulse width	0.41	0.48	0.48	1.37	ns, Min
T _{RQ}	Delay from SR input to AQ – DQ flip-flops	0.60	0.70	0.70	0.88	ns, Max
T _{CEO}	Delay from CE input to AQ – DQ flip-flops	0.60	0.65	0.65	0.90	ns, Max
F _{TOG}	Toggle frequency (for export control)	862	806	667	500	MHz

Table 52: PLL Specification (Cont'd)

Symbol	Description	Device ⁽¹⁾	Speed Grade				Units
			-3	-3N	-2	-1L	
F _{INMIN}	Minimum Input Clock Frequency	LX devices	19	19	19	19	MHz
		LXT devices	19	19	19	N/A	MHz
F _{INJITTER}	Maximum Input Clock Period Jitter: 19–200 MHz	All	1 ns Maximum				
	Maximum Input Clock Period Jitter: > 200 MHz	All	<20% of clock input period Maximum				
F _{INDUTY}	Allowable Input Duty Cycle: 19—199 MHz	All	25/75				%
	Allowable Input Duty Cycle: 200—299 MHz	All	35/65				%
	Allowable Input Duty Cycle: > 300 MHz	All	45/55				%
F _{VCOMIN}	Minimum PLL VCO Frequency	LX devices	400	400	400	400	MHz
		LXT devices	400	400	400	N/A	MHz
F _{VCOMAX}	Maximum PLL VCO Frequency	LX devices	1080	1050	1000	1000	MHz
		LXT devices	1080	1050	1000	N/A	MHz
F _{BANDWIDTH}	Low PLL Bandwidth at Typical ⁽³⁾	All	1	1	1	1	MHz
	High PLL Bandwidth at Typical ⁽³⁾	All	4	4	4	4	MHz
T _{STAPHAOFFSET}	Static Phase Offset of the PLL Outputs	All	0.12	0.12	0.12	0.15	ns
T _{OUTJITTER}	PLL Output Jitter ⁽³⁾	All	Note 2				
T _{OUTDUTY}	PLL Output Clock Duty Cycle Precision ⁽⁴⁾	All	0.15	0.15	0.20	0.25	ns
T _{LOCKMAX}	PLL Maximum Lock Time	All	100	100	100	100	µs
F _{OUTMAX}	PLL Maximum Output Frequency for BUFGMUX	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz
	PLL Maximum Output Frequency for BUFPLL	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz
F _{OUTMIN}	PLL Minimum Output Frequency ⁽⁵⁾	All	3.125	3.125	3.125	3.125	MHz
T _{EXTFDVAR}	External Clock Feedback Variation: 19–200 MHz	All	1 ns Maximum				
	External Clock Feedback Variation: > 200 MHz	All	< 20% of clock input period Maximum				
RST _{MINPULSE}	Minimum Reset Pulse Width	All	5	5	5	5	ns
F _{PFDMAX} ⁽⁵⁾	Maximum Frequency at the Phase Frequency Detector	LX devices	500	500	400	300	MHz
		LXT devices	500	500	400	N/A	MHz
F _{PFDMIN}	Minimum Frequency at the Phase Frequency Detector	LX devices	19	19	19	19	MHz
		LXT devices	19	19	19	N/A	MHz
T _{FBDELAY}	Maximum Delay in the Feedback Path	All	3 ns Max or one CLKIN cycle				

Notes:

1. LXT devices are not available with a -1L speed grade.
2. Values for this parameter are available in the Clocking Wizard.
3. The PLL does not filter typical spread spectrum input clocks because they are usually far below the bandwidth filter frequencies.
4. Includes global clock buffer.
5. Calculated as $F_{VCO}/128$ assuming output duty cycle is 50%.
6. When using CLK_FEEDBACK = CLKOUT0 with BUFIO2 feedback, the feedback frequency will be higher than the phase frequency detector frequency. $F_{PFDMAX} = F_{CLKFB} / CLKFBOUT_MULT$

Spartan-6 Device Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. The representative values for typical pin locations and normal clock loading are listed in Table 70 through Table 77. Values are expressed in nanoseconds unless otherwise noted.

Table 70: Global Clock Setup and Hold Without DCM or PLL (No Delay)

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVC MOS25 Standard.(1)							
T _{PSND} / T _{PHND}	No Delay Global Clock and IFF(3) without DCM or PLL	XC6SLX4	0.10/1.56	N/A	0.10/1.83	0.07/2.54	ns
		XC6SLX9	0.10/1.56	0.10/1.57	0.10/1.84	0.07/2.54	ns
		XC6SLX16	0.12/1.42	0.12/1.48	0.12/1.64	0.13/2.19	ns
		XC6SLX25	0.18/1.64	0.18/1.75	0.18/1.99	0.11/2.57	ns
		XC6SLX25T	0.18/1.64	0.18/1.75	0.18/1.99	N/A	ns
		XC6SLX45	-0.08/1.80	-0.08/1.95	-0.08/2.27	-0.17/2.74	ns
		XC6SLX45T	-0.08/1.80	-0.08/1.95	-0.08/2.27	N/A	ns
		XC6SLX75	0.13/1.81	0.13/2.06	0.13/2.27	-0.12/3.30	ns
		XC6SLX75T	0.13/1.81	0.13/2.06	0.13/2.27	N/A	ns
		XC6SLX100	-0.14/2.03	-0.14/2.24	-0.14/2.56	-0.17/3.44	ns
		XC6SLX100T	-0.14/2.03	-0.14/2.24	-0.14/2.56	N/A	ns
		XC6SLX150	-0.24/2.42	-0.24/2.74	-0.24/2.95	-0.60/3.75	ns
		XC6SLX150T	-0.24/2.42	-0.24/2.74	-0.24/2.95	N/A	ns
		XA6SLX4	0.10/1.57	N/A	0.10/1.84	N/A	ns
		XA6SLX9	0.10/1.57	N/A	0.10/1.84	N/A	ns
		XA6SLX16	0.12/1.43	N/A	0.12/1.64	N/A	ns
		XA6SLX25	0.18/1.65	N/A	0.18/1.99	N/A	ns
		XA6SLX25T	0.18/1.65	N/A	0.18/1.99	N/A	ns
		XA6SLX45	-0.08/1.82	N/A	-0.08/2.27	N/A	ns
		XA6SLX45T	-0.08/1.82	N/A	-0.08/2.27	N/A	ns
		XA6SLX75	0.13/2.02	N/A	0.13/2.32	N/A	ns
		XA6SLX75T	0.13/2.02	N/A	0.13/2.32	N/A	ns
		XA6SLX100	N/A	N/A	0.10/2.51	N/A	ns
		XQ6SLX75	N/A	N/A	0.13/2.32	-0.12/3.30	ns
		XQ6SLX75T	0.13/2.02	N/A	0.13/2.32	N/A	ns
		XQ6SLX150	N/A	N/A	-0.24/2.95	-0.60/3.75	ns
		XQ6SLX150T	-0.24/2.74	N/A	-0.24/2.95	N/A	ns

Notes:

- Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage.
- IFF = Input Flip-Flop or Latch.

Table 79: Package Skew (Cont'd)

Symbol	Description	Device	Package ⁽²⁾	Value	Units
T _{PKGSKEW}	Package Skew ⁽¹⁾	LX45	CSG324	70	ps
			CS(G)484	99	ps
			FG(G)484	109	ps
			FG(G)676	138	ps
		LX45T	CSG324	75	ps
			CS(G)484	100	ps
			FG(G)484	95	ps
		LX75	CS(G)484	101	ps
			FG(G)484	107	ps
			FG(G)676	161	ps
		LX75T	CS(G)484	107	ps
			FG(G)484	110	ps
			FG(G)676	134	ps
		LX100	CS(G)484	95	ps
			FG(G)484	155	ps
			FG(G)676	144	ps
		LX100T	CS(G)484	88	ps
			FG(G)484	111	ps
			FG(G)676	147	ps
			FG(G)900	134	ps
		LX150	CS(G)484	84	ps
			FG(G)484	103	ps
			FG(G)676	115	ps
			FG(G)900	121	ps
		LX150T	CS(G)484	83	ps
			FG(G)484	88	ps
			FG(G)676	141	ps
			FG(G)900	120	ps

Notes:

- These values represent the worst-case skew between any two SelectIO resources in the package: shortest delay to longest delay from Pad to Ball.
- Some of the devices are available in both Pb and Pb-free (additional G) packages as standard ordering options. See [DS160: Spartan-6 Family Overview](#) for more information.

Table 80: Sample Window

Symbol	Description	Device ⁽¹⁾	Speed Grade				Units
			-3	-3N	-2	-1L	
T _{SAMP}	Sampling Error at Receiver Pins ⁽²⁾	All	510	510	530	740	ps
T _{SAMP_BUFIO2}	Sampling Error at Receiver Pins using BUFIO2 ⁽³⁾	All	430	430	450	590	ps

Notes:

- LXT devices are not available with a -1L speed grade.
- This parameter indicates the total sampling error of Spartan-6 FPGA DDR input registers, measured across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
 - CLK0 DCM jitter
 - DCM accuracy (phase offset)
 - DCM phase shift resolution
These measurements do not include package or clock tree skew.
- This parameter indicates the total sampling error of Spartan-6 FPGA DDR input registers, measured across voltage, temperature, and process. The characterization methodology uses the BUFIO2 clock network and IODELAY2 to capture the DDR input registers' edges of operation. These measurements do not include package or clock tree skew.

Date	Version	Description of Revisions
01/10/11	1.11	Production release of XC6SLX4 and XC6SLX9 in the specific speed grades listed in Table 26 and Table 27 using ISE v12.4 software with speed specification v1.15 for the -4, -3, -3N, and -2 speed grades. Added note 3 to Table 27. Also updated the -1L speed grade requirements to ISE v12.4 software with speed specification v1.06. Revised -3N definition throughout the document. Added note 4 to Table 2 and updated note 5. Added information on V_{CCINT} to note 1 in Table 5. Updated Networking Applications -3 values in Table 25 to match improvements made in ISE v12.4. In Table 28, added note 1 and revised the T_{IOTP} values for LVDS_33, LVDS_25, MINI_LVDS_33, MINI_LVDS_25, RSDS_33, RSDS_25, TMDS_33, PPDS_33, and PPDS_25. Added note 3 to Table 55.
02/11/11	1.12	As described in XCEN11008: Product Discontinuation Notice For Spartan-6 LXT -4 Devices, the -4 speed specifications have been discontinued. As outlined in page 2 of the XCN, designers currently using -4 speed specifications should rerun timing analysis using the new -3 speed specifications before moving to a replacement device. Updated the networking applications section of Table 25. Updated -2 speed specifications throughout document and added note 3 to Table 27 advising designers to use the -2 speed specification update (v1.17) with the ISE 12.4 software patch. Added F_{CLKDIV} to Table 37 and Table 38. Updated note 2 in Table 39. Updated units for $T_{SMCKCSO}$ and T_{BPICCO} in Table 47. Updated -1L in Table 71. Removed Note 2: <i>Package delay information is available for these device/package combinations. This information can be used to deskew the package</i> from Table 79.
03/31/11	2.0	Production release of XC6SLX45 in the -1L speed grades listed in Table 26 and Table 27 using ISE v13.1 software with -1L speed specification v1.06. In Table 39, removed values in the -1L column and added note 3 as IODELAY2 only supports Tap0 for lower-power devices. Updated copyright page 1 and Notice of Disclaimer.
05/20/11	2.1	Production release of XC6SLX100 and XC6SLX150 in the specific speed grades listed in Table 26 and Table 27 using ISE v13.1 software with -1L speed specification v1.06. Updated Table 27 and Note 7 with changes per XCEN11012: Speed File Change for -3N Devices. Revised Switching Characteristics section for speed specifications: v1.18 for -3, -3N, and -2; including improvements in Table 73 through Table 77 and Table 81. Removed <i>Memory Controller Block</i> from the performance heading in Table 2 and revised Note 2. In Table 4, added Note 1 to C_{IN} and updated the description of R_{IN_TERM}. Updated Note 1 in Table 5. Updated Note 1 of Table 7. In Table 25, added and removed -1L specifications, increased the standard performance DDR3 specifications, removed the extended performance DDR3 row and updated Note 3 and Note 4. Clarified the introductory information for Table 28 and Table 30. In Table 32: Revised V_{MEAS} value for LVCMOS12; revised V_{REF} for LVDS_25, LVDS_33, BLVDS_25, MINI_LVDS_25, MINI_LVDS_33, RSDS_25, and RSDS_33; revised R_{REF} for BLVDS_25 and TMDS_33; and added Note 4 and Note 5. Updated Note 2 and Note 3 in Table 39. In Table 47, revised the values and description of T_{POR} including adding Note 3. Also in Table 47, augmented the description and added specifications for F_{RBCK} and removed XC6SLX4 from F_{MCCK} (maximum frequency, parallel mode (Master SelectMAP/BPI)). Added BUFGMUX to Table 48 title. Added Table 50. In Table 52, revised specifications for $T_{EXTFVAR}$ and $F_{INJITTER}$. In Table 54 removed the 5 MHz < CLKIN_FREQ_DLL parameter in the LOCK_DLL description. In both Table 56 and Table 57, removed the 5 MHz < F_{CLKIN} parameter in the LOCK_FX description. In Table 58, updated description for PSCLK_FREQ and PSCLK_PULSE. Revised title and symbol of Table 70, added new speed specifications for -1L, and added Note 2. Added Table 71.
07/11/11	2.2	Added the Automotive XA Spartan-6 and Defense-grade Spartan-6Q devices to all appropriate tables while sometimes removing the XC6S nomenclature. Added expanded temperature range (Q) to all appropriate tables. Updated T_{SOL} packages in Table 1. Added R_{OUT_TERM} to Table 4. Updated Note 2 on Table 13. Production release of the XC6SLX4, XC6SLX9, XC6SLX16, XC6SLX25, XC6SLX75, XQ6SLX75, and XQ6SLX150 in Table 26 and Table 27 using ISE v13.2 software with -1L speed specification v1.07. Production release of the XA6SLX16, XA6SLX25T, XA6SLX45, XA6SLX45T, XQ6SLX75, XQ6SLX75T, XQ6SLX150, and XQ6SLX150T in Table 26 and Table 27 using ISE v13.2 software with -2 and -3 speed specification v1.19. Added Table 29: IOB Switching Characteristics for the Automotive XA Spartan-6 and the Spartan-6Q Devices(1). Updated CS(G)484 from CSG484 throughout data sheet. Clarified Note 3 in Table 39.
08/08/11	2.3	Production release of the XA6SLX25, XA6SLX75, and XA6SLX75T in Table 26 and Table 27 using ISE v13.2 software with -2 and -3 speed specification v1.19.

Date	Version	Description of Revisions
09/14/11	2.4	Production release of the XA6SLX4 and XA6SLX9 devices in Table 26 and Table 27 using ISE v13.2 software with -2 and -3 speed specification v1.19. Added production released version of the XA6SLX100 to Table 26 and Table 27 using ISE v13.3 software with -2 speed specification v1.20. Updated R_{OUT_TERM} description in Table 4. Fixed the LVPECL V_H error in Table 31. Updated introduction in Simultaneously Switching Outputs. Added the XA6SLX100 to Table 63 through Table 78, and Table 81. Added Note 4 to Table 78 because the T_{CKSKEW} for the XC6SLX100 is not the same as the T_{CKSKEW} for the XA6SLX100. Revised the revision history for version 1.6 dated 06/24/10. Removed the parenthetical statement about the -3N speed grade: (specifications are identical to the -3 speed grade).
10/17/11	3.0	Changed the data sheet from Preliminary Product Specification to Product Specification. Updated the Switching Characteristics, page 19 speed specification version ISE v13.3 software to -2 and -3 speed specification v1.20 and -1L speed specification of v1.08. Also updated Note 1 in Table 27. In Table 43, <i>Block RAM Switching Characteristics</i>, the F_{MAX} value for the -2 speed grade has been changed from 260 MHz to 280 MHz. In Table 54, <i>Switching Characteristics for the DLL</i>, a Note 6 was added and linked to CLKIN_CLKFB_PHASE.